TOYOBO MC Corporation
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November 4, 2025

To exhibit VYLOSHOT®, Low-pressure encapsulation molding material, at productronica 2025

TOYOBO MC Corporation will exhibit jointly with Toyobo STC Co., Ltd. at "productronica 2025," to be held in Munich, Germany from Tuesday, November 18 to Friday, November 21, 2025. Our company will showcase its a low-pressure encapsulation molding material "VYLOSHOT®", which is used for sealing electronic components and sensors in automotive and factory automation (FA) equipment applications.

"productronica 2025"is one of the world's leading trade fairs in the electronics sector. It is organized into five thematic zones, and our company will participate in the "PCB & EMS Cluster" zone.

VYLOSHOT® is a low-pressure encapsulation molding material designed to protect printed circuit boards and electronic components. It is widely used in electronics and automotive applications for waterproofing and dustproofing. With high fluidity and the ability to mold under low pressure, it minimizes damage on electronic components. Furthermore, its short cooling and curing time significantly enhances productivity compared to conventional two-component curing resins.

Molded products sealed using VYLOSHOT® encapsulant technology

At the exhibition booth, we will display molded samples sealed with VYLOSHOT® to highlight the product's key features, including flexibility, thin-wall moldability, excellent flowability, and long-term durability.

1. Products

- VYLOSHOT® (Low-pressure encapsulation molding material)

2. About the Exhibition

- Duration　: November 18–21, 2025　9:00–18:00（Final Day 9:00–16:00）
- Place　: Trade Fair Center Messe München
- Booth No.　: B3.376(Toyobo STC Booth)
- Organizer　: Messe München GmbH
- Exhibition website : productronica 2025

■Contact information
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